

## 2.0x1.25x0.8mm Chip LED

# **OSXX0805C1E**

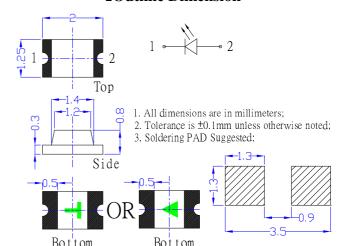
#### **■Features**

- Single chip
- 2.0x1.25x0.8mm(0805) standard package.
- Suitable for all SMT assembly methods.
- Compatible with infrared and vapor phase reflow solder process.
- This product doesn't contain restriction
  Substance, comply ROHS standard.
- Compatible with automatic placement equipment.

## Applications

- Automotive : Dashboards, stop lamps, turn signals.
- Backlighting: LCDs, Key pads advertising.

#### **■Outline Dimension**

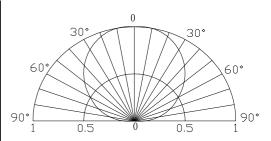


## ■Absolute Maximum Rating

#### (Ta=25°C)

#### Value Item Symbol Unit W/M//K/V/B/G5 G8/Y5/O5/R5 DC Forward Current 20 20 $I_F$ mAPulse Forward Current# 100 100 $I_{FP}$ mΑ Reverse Voltage $V_R$ 5 5 V Power Dissipation $P_{D}$ 68 48 mW $^{\circ}$ C Operating Temperature -40 ~ +85 Topr $^{\circ}$ C Storage Temperature -40~ +85 Tstg Lead Soldering Temperature Tsol 260°C/10sec

# **■**Directivity



#Pulse width Max 0.1ms, Duty ratio max 1/10

#### **■**Electrical -Optical Characteristics

#### (Ta=25°C

				$V_{F}(V)$			$I_R(\mu A)$	Iv(mcd)		λD(nm)		2θ1/2(deg)		
Part Number	Colo	ſ		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.
				I	F=10m	4	V <sub>R</sub> =5V				I <sub>F</sub> =10mA			
OSW40805C1E	Pure White	W4		-	2.8	3.4	10	200	250	-	X:0.31, Y:0.33		120	
OSW50805C1E	White	W5		-	2.8	3.4	10	200	250	-	X:0.27, Y:0.28		120	
OSM50805C1E	Warm White	M5		-	2.8	3.4	10	200	250	-	X:0.44, Y:0.41		120	
OSK50805C1E	Pink	K5		-	2.8	3.4	10	35	50	-	X:0.38, Y:0.18		120	
OSV40805C1E	Violet	V4		-	2.8	3.4	10	5	7	-	395	400	405	120
OSB50805C1E	Blue	В5		-	2.8	3.4	10	45	65	-	460	465	475	120
OSG50805C1E	True Green	G5			2.8	3.4	10	200	250	-	520	525	530	120
OSG80805C1E	Yellow Green	G8		ı	1.8	2.4	10	12	20	ı	564	570	578	120
OSY50805C1E	Yellow	Y5		1	1.8	2.4	10	60	70	ı	585	590	595	120
OSO50805C1E	Orange	O5		ı	1.8	2.4	10	60	70	1	600	605	610	120
OSR50805C1E	Red	R5		-	1.8	2.4	10	60	70	1	620	625	630	120

<sup>\*1</sup> Tolerance of measurements of chromaticity coordinate is  $\pm 10\%$  \*2 Tolerance of measurements of dominant wavelength is  $\pm 1$ nm

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<sup>\*3</sup> Tolerance of measurements of luminous intensity is ±15% \*4 Tolerance of measurements of forward voltage is±0.1V



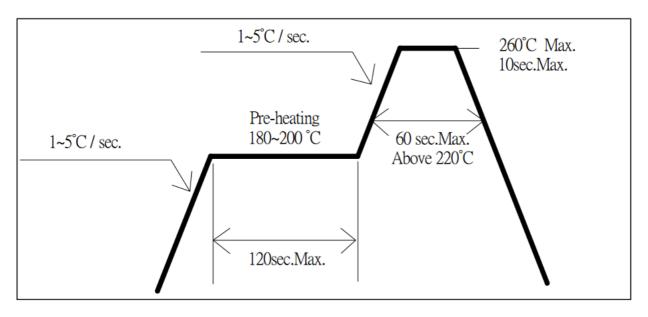
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#### **■ Soldering Conditions**

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ∼ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak temperature	260°C Max.	Temperature	350°C Max.		
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.		
Condition	Refer to Temperature-profile		(one time only)		

# • Reflow Soldering Condition(Lead-free Solder)



- \*Recommended soldering conditions vary according to the type of LED
- \*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- \*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

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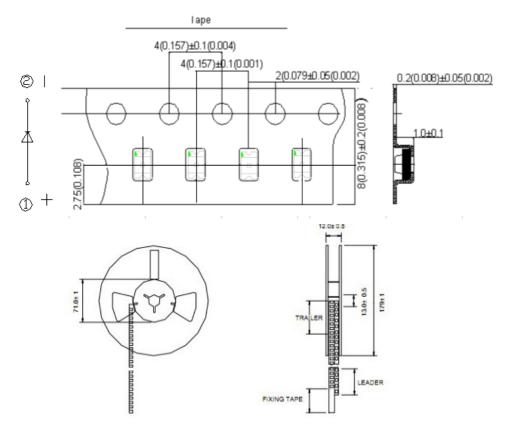


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#### OSXX0805C1E

#### ■ Taping and Orientation.

- 1. Quantity:3000pcs/Reel
- 2. Note: The tolerances unless mentioned is ±0.1mm,Unit:mm



#### **■ Cautions:**

- 1. After open the package, the LED's floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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